



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-05-06
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Emilio Castelli	Representative Title	APG MD CHAMPION
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
L9678P	B95W*UAE3CBP	A	MU1A	2016-05-06
Amount	UoM	Unit type	ST ECOPACK Grade	
349.70	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte, annealed	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFP	10X10X1.4	64	FLAT	
Comment				

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-16th June 2014				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	B95W*UAE3CBP					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or Dies	Other inorganic materials	14.234	mg	supplier	die	Silicon (Si)	7440-21-3		12.710	mg	892932	36345
Die or Dies				supplier	metallization	Aluminium (Al)	7429-90-5		0.030	mg	2108	86
Die or Dies				supplier	metallization	Copper (Cu)	7440-50-8		0.782	mg	54939	2236
Die or Dies				supplier	metallization	Cobalt (Co)	7440-48-4		0.001	mg	70	3
Die or Dies				supplier	metallization	Titanium (Ti)	7440-32-6		0.008	mg	562	23
Die or Dies				supplier	metallization	Tungsten (W)	7440-33-7		0.045	mg	3161	129
Die or Dies				supplier	metallization	Nickel (Ni)	7440-02-0		0.097	mg	6815	277
Die or Dies				supplier	metallization	Platinum (Pt)	7440-06-4		0.054	mg	3794	154
Die or Dies				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.026	mg	1827	74
Die or Dies				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.195	mg	13700	558
Die or Dies				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.007	mg	492	20
Die or Dies				supplier	back side metallization	Gold (Au)	7440-57-5		0.019	mg	1335	54
Die or Dies				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.065	mg	4567	186
Die or Dies				supplier	glass coating	Glass: Silicon Dioxide (SiO2)	7631-86-9		0.195	mg	13700	558
Leadframe	Copper & its alloys	99.320	mg	supplier	alloy	Copper (Cu)	7440-50-8		93.170	mg	938079	266428
Leadframe				supplier	alloy	Nickel (Ni)	7440-02-0		2.906	mg	29259	8310
Leadframe				supplier	alloy	Magnesium (Mg)	7439-95-4		0.145	mg	1460	415
Leadframe				supplier	alloy	Silicon (Si)	7440-21-3		0.630	mg	6343	1802
Leadframe				supplier	metallization	Silver (Ag)	7440-22-4		2.469	mg	24859	7060
Die attach		3.102	mg	supplier	glue or tape	Isobornyl Methacrylate	7534-94-3		0.171	mg	55126	489
Die attach				supplier	glue or tape	Bismaleimide resin	na		0.124	mg	39974	355
Die attach				supplier	glue or tape	Silver (Ag)	7440-22-4		2.807	mg	904900	8027
Bonding wire				supplier	wire	Copper (Cu)	7440-50-8		0.777	mg	1000000	2222
encapsulation		228.446	mg	supplier	mold compound	Solid Epoxy Resin	na		17.573	mg	76924	50252
encapsulation				supplier	mold compound	Phenol Resin	na		17.573	mg	76924	50252
encapsulation				supplier	mold compound	Silica, vitreous	60676-86-0		191.324	mg	837502	547109
encapsulation				supplier	mold compound	Carbon-black	1333-86-4		1.098	mg	4806	3140
encapsulation				supplier	mold compound	Bismuth (Bi)	7440-69-9		0.878	mg	3843	2511
connections coating	Solder	3.565	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		3.565	mg	1000000	10194